



深圳市聚峰锡制品有限公司

JUFENG SHENZHEN JUFENG SOLDER CO., LTD.

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Technical Data Sheet for Solder Flux Paste

Model: JF15304

1. Product Description

JF15304 BGA Flux is a type ROL1 formulation designed for BGA rework requiring high-reliability, stability and cleanliness. It is a No Clean flux ideally suited for BGA and surface mount component repairs. It leaves a clear colorless residue which does not require cleaning. It is designed for a wide range of temperature and humidity conditions with a stencil life greater than 8 hours.

2. Advantages

- Stable product with long stencil life
- Excellent printing characteristics
- Suitable for dispensing, stencil printing, and pin transfer
- Excellent SMT rework flux offering bright shiny solder joints with clear probable residue
- Excellent wetting on all surface finishes

3. Application

- BGA rework and repair
- Sphere attachment to BGA
- Surface Mount Device Pads
- Switches
- Sockets

4. Typical Product Data and physical properties

Flux Type	No Clean, ROL1
Flash Point (TCC)	>140°C(°F)
Appearance	Slight Yellow
Odor	Slight

5. Packaging

10cc syringe

100g jars

6. Storage and Disposal

Paste flux must be stored in a sealed container and disposed of in accordance with local authority requirements.